

TOSHIBA PHOTOCOUPLER

TLP3064(D4)SERIES

ATTACHMENT : SPECIFICATIONS FOR VDE0884 OPTION (D4)

Types : TLP3064, TLP3064F

Type designations for 'Option : (D4)', which are tested under VDE0884 requirements.

Ex. : TLP3064 (D4-LF1) D4 : VDE0884 option
 LF1 : lead bend

Note : Use Toshiba standard type number for safety standard application.

Ex. TLP3064 (D4-LF1) → TLP3064



VDE0884 ISOLATION CHARACTERISTICS

DESCRIPTION	SYMBOL	RATING	UNIT
Application Classification (DIN VDE0110 Teil 1/01.89, Table 1) for rated mains voltage ≤ 300 V _{RMS} for rated mains voltage ≤ 600 V _{RMS}		I-IV I-III	—
Climatic Classification (DIN IEC68 Teil 1/09.80)		40 / 100 / 21	—
Pollution Degree (DIN VDE0110 Teil 2/01.89)		2	—
Maximum Operating Insulation Voltage Type 1 (7.62) (TLP3064 type) Type 2 (10.16) (TLP3064F type)	V _{IORM}	890 1140	V _{pk}
Input to output Test Voltage, Method A U _{pr} = 1.5 × V _{IORM} , Type and Sample Test t _p = 60s, Partial Discharge < 5pC Type 1 (7.62) (TLP3064 type) Type 2 (10.16) (TLP3064F type)	V _{pr}	1335 1710	V _{pk}
Input to output Test Voltage, Method B U _{pr} = 1.875 × V _{IORM} , 100% Production Test t _p = 1s, Partial Discharge < 5pC Type 1 (7.62) (TLP3064 type) Type 2 (10.16) (TLP3064F type)	V _{pr}	1670 2140	V _{pk}
Highest Permissible Overvoltage (Transient Overvoltage, t _{pr} = 10s)	V _{TR}	8000	V _{pk}
Safety Limiting Values (Max. permissible ratings in case of fault, also refer to thermal derating curve Current (Input current I _F , P _s = 0) Power (Output or Total Power Dissipation) Temperature	I _{si} P _{si} T _{si}	400 700 150	mA mW °C
Insulation Resistance, V _{IO} = 500V, T _a = 25°C V _{IO} = 500V, T _a = T _{si}	R _{si}	$\geq 10^{12}$ $\geq 10^9$	Ω

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INSULATION RELATED SPECIFICATIONS

		 Type 1 (7.62) (TLPxxx type)	 Type 2 (10.16) (TLPxxxF type)
Minimum Creepage Distance *	Cr	7.0 mm	8.0 mm
Minimum Clearance *	Cl	7.0 mm	8.0 mm
Minimum Insulation Thickness	ti	0.5 mm	
Comperative Tracking Index (DIN IEC112/VDE0303, Part 1)	CTI	175 (VDE0110 Teil 2/01.89 Group III a)	

* in accordance with DIN VDE0110 Teil 2/01.89, Table 2, & 4

1. If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value (e. g. at a standard distance between soldering eye centres of 7.5mm). If this is not permissible, the user shall take suitable measures.
2. This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.

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VDE Test sign : Marking on product for VDE0884 :



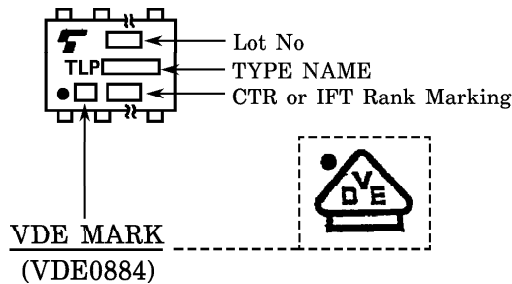
Marking on packing for VDE0884 :



0884

Marking Example

TLP3064,3064F



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Figure 1 Partial discharge measurement procedure according to VDE0884
Destructive test for qualification and sampling tests.

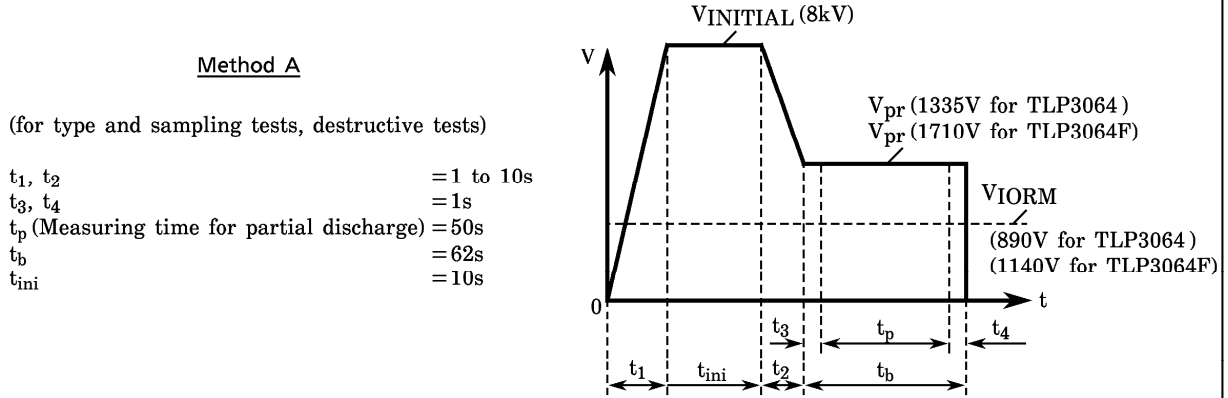


Figure 2 Partial discharge measurement procedure according to VDE0884
Non-destructive test for 100% inspection.

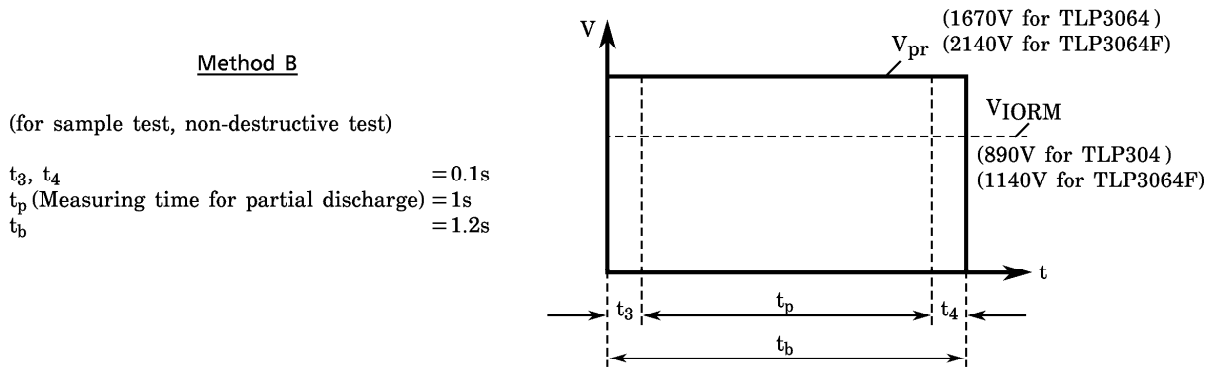


Figure 3 Dependency of maximum safety ratings on ambient temperature

